



Material Content Data Sheet



Sales Product Name		ICE2QR1765Z		Issued		1. August 2018		
MA#		MA001860904						
Package		PG-DIP-7-3		Weight*		645.05 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.659	0.57	0.57	5672	5672
leadframe	inorganic material	phosphorus	7723-14-0	0.048	0.01		75	
	non noble metal	zinc	7440-66-6	0.194	0.03		300	
	non noble metal	iron	7439-89-6	3.872	0.60		6003	
wire	non noble metal	copper	7440-50-8	157.218	24.37	25.01	243731	250109
	noble metal	gold	7440-57-5	0.407	0.06	0.06	631	631
	encapsulation	organic material	carbon black	1333-86-4	2.349	0.36		3641
encapsulation	plastics	epoxy resin	-	63.419	9.83		98316	
	inorganic material	silicondioxide	60676-86-0	404.001	62.64	72.83	626312	728269
leadfinish	non noble metal	tin	7440-31-5	6.460	1.00	1.00	10014	10014
plating	noble metal	silver	7440-22-4	1.594	0.25	0.25	2471	2471
glue	plastics	epoxy resin	-	0.320	0.05		496	
	noble metal	silver	7440-22-4	1.508	0.23	0.28	2338	2834
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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